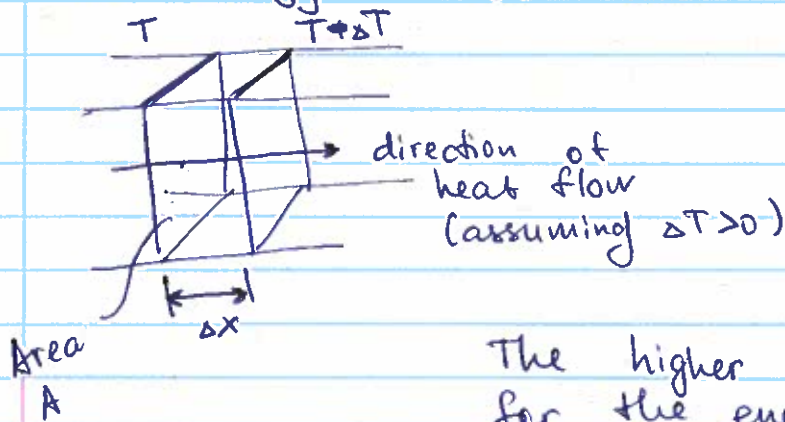


# Heat transfer mechanisms

1. Convection - energy transferred by the movement of a warm substance
2. Thermal conduction - energy is transferred through kinetic energy exchange between microscopic particles (spontaneously)

Reminder: energy flows from hot to cold

The energy transfer rate (power)  $P = k \cdot A \frac{dT}{dx}$



$k$  - thermal conductivity

$$P = \frac{\Delta Q}{\Delta t} = k \cdot A \frac{\Delta T}{\Delta x}$$

The higher is  $k$ , the easier it is for the energy to flow

Max  $k$  - metals, as free electrons carry energy

The flowing heat will affect the temperature  $T$  gradient, in a sample  $T(x, t)$  depends of time and  $x$   
Heat equation

$$\frac{\partial T(x, t)}{\partial t} = \frac{k}{c \cdot \rho} \frac{\partial^2 T(x, t)}{\partial x^2}$$

$k$ - thermal conductivity	] material constants
$c$ - specific heat capacity	
$\rho$ - density	

Example: a bar of length  $L$  has fixed temperature at both ends

a) Steady state solution  $\frac{\partial T}{\partial t} = 0$   $\frac{\partial^2 T}{\partial x^2} = 0$   
 $T(x) = a + bx$



Boundary conditions:  $T(0) = a$   $T(L) = a + b \cdot L$

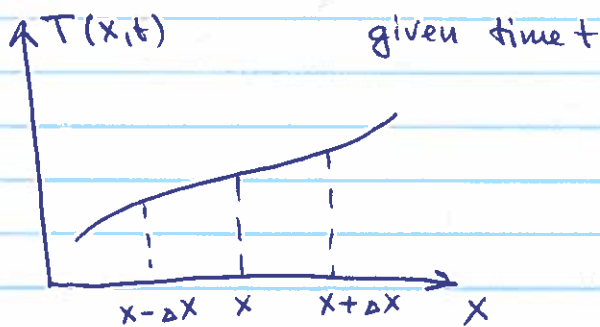
Solution:  $T(x) = T(0) + x \cdot \frac{T(L) - T(0)}{L}$

b) Let's allow the temperature of one end to change in time  $T(0, t)$

In this case we have to solve the heat equation, often numerically

$$\frac{\partial T(x, t)}{\partial t} = \frac{k}{c \rho} \cdot \frac{\partial^2 T(x, t)}{\partial x^2}$$

rate of change in local temperature



Numerical derivative

$$\frac{\partial T}{\partial x} \Big|_- \rightarrow \frac{T(x) - T(x - \Delta x)}{\Delta x}$$

$$\frac{\partial T}{\partial x} \Big|_+ \rightarrow \frac{T(x + \Delta x) - T(x)}{\Delta x}$$

$$\frac{\partial^2 T}{\partial x^2} = \frac{\frac{\partial T}{\partial x} \Big|_+ - \frac{\partial T}{\partial x} \Big|_-}{\Delta x} = \frac{T(x + \Delta x) + T(x - \Delta x) - 2T(x)}{(\Delta x)^2}$$

$$\frac{\partial T(x, t)}{\partial t} \approx \frac{T(x, t + \Delta t) - T(x, t)}{\Delta t} = \frac{k}{c \rho} \frac{[T(x + \Delta x) + T(x - \Delta x) - 2T(x)]}{(\Delta x)^2}$$

$$T(x, t + \Delta t) = T(x, t) + \frac{k}{c \rho} \frac{\Delta t}{(\Delta x)^2} [T(x + \Delta x, t) + T(x - \Delta x, t) - 2T(x, t)]$$

constant coefficient digital derivative

## Thermal Conductivities for Various Materials

Material	Thermal Conductivity (J / s·m·°C)
Diamond	1,600
Silver	420
Copper	390
Brass	110
Lead	35
Steel	14.0
Glass	0.80
Water	0.60
Body fat	0.20
Wood	0.15
Wool	0.04
Air	0.0256
Styrofoam	0.01

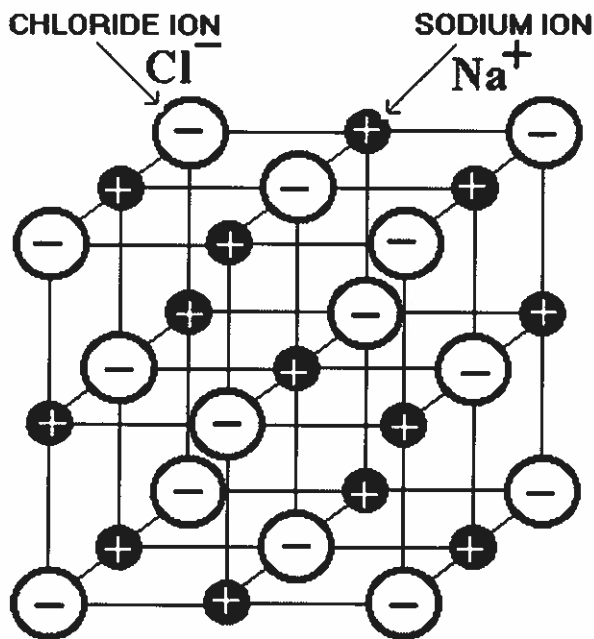
Material	Thermal conductivity at 25°C (W/m K)	Specific heat capacity	
		(J/kg K)	(J/m <sup>3</sup> K)
PA 6	0.25	1600	1824
PLA	0.13	1800	2340
Air	0.024	1005	1231
Wood (oak)	0.17	2000	1833
Steel	43	490	3822
Aluminium	205	870	2484
Water	0.58	4182	4190
Concrete	1.7	880	2122

**TABLE 20.1** Electrical Resistivity and Thermal Conductivity of Copper and Other Pure Commercial Metals at 293 K.

	Electrical Resistivity	Thermal Conductivity	Relative Electrical Conductivity	Relative Thermal Conductivity
(Metal 100)	at 293 K, $\mu\Omega\text{cm}$	$\text{Wm}^{-1}\text{k}^{-1}$	(Copper = 100)	(Copper = 100)
Silver	1.63	419	104	106
Copper	1.694	397	100	100
Gold	2.2	316	77	80
Aluminum	2.67	238	63	60
Beryllium	3.3	194	51	49
Magnesium	4.2	155	40	39
Tungsten	5.4	174	31	44
Zinc	5.96	120	28	30
Nickel	6.9	89	24	22
Iron	10.1	78	17	20
Platinum	10.58	73	16	18
Tin	12.6	73	13	18
Lead	20.6	35	8.2	8.8
Titanium	54	22	3.1	5.5
Bismuth	117	9	1.4	2.2

Adapted from Brandes, E. A., Ed., *Smithells Metals Reference Book*, Sixth Edition, Butterworth, Inc. 1983. (Used by permission.)

## Insulator



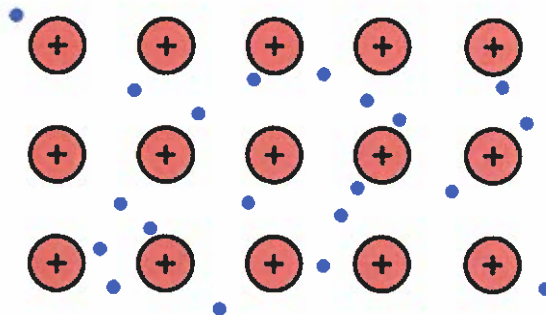
SODIUM CHLORIDE LATTICE STRUCTURE

All electrons are captured,  
very few free electrons

~~They add~~

Energy travels in a form  
of lattice oscillations  
that are slower

## Conductor



(Valence)

Electrons are free  
to move.

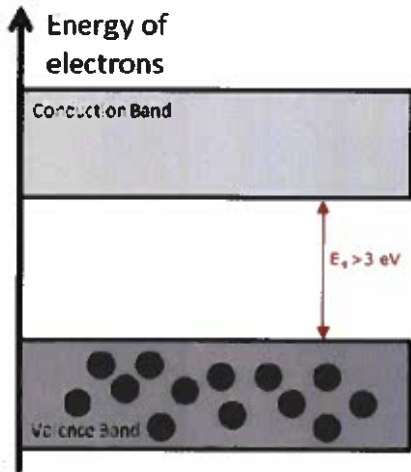
Can be modeled as  
ideal gas

Any heat flow first  
transfer the energy  
to the electrons, that  
quickly spread it  
throughout the volume,  
then thermalize with heavier  
ions.

**Insulator**

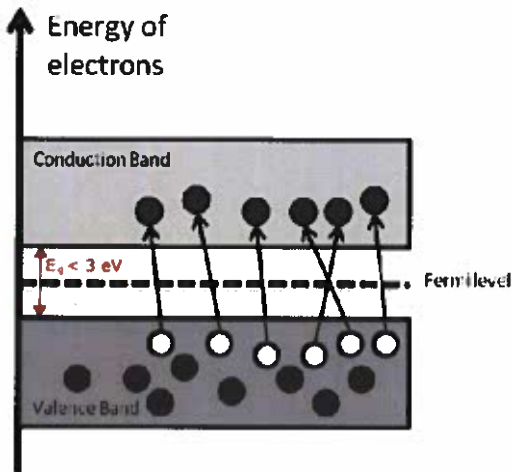
**Semiconductor**

**Conductor**



$E_g$  - band gap width

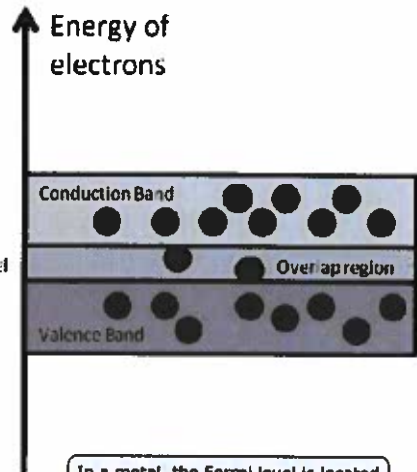
High energy gap between valence and conduction bands is an insulator at normal temperature, electrons can reach the conduction band.



Fermi level - last occupied energy level at  $T = 0$

In semiconductors, the gap is small enough, the thermal energy can overcome some of the electrons.

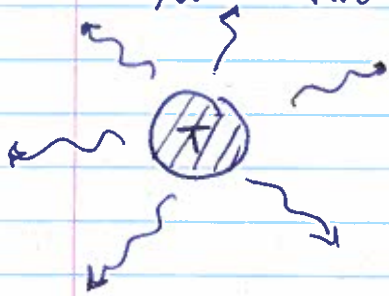
At high temperatures, electrons in the valence band can be thermally excited to the conduction band, material becomes electrically conductive.



In a metal, the Fermi level is located within the permitted band, so it is good conductor of electricity at any temperature.

In conductors, there is no gap the valence band to the conduction band overlap.

Radiation - energy is transferred through emission and absorption of electro-magnetic waves. Does not require any material contact b/w two objects



Emitted power  $P = \sigma \cdot A \cdot e \cdot T^4$   
 $\sigma = 5.67 \cdot 10^{-8} \text{ W/m}^2\text{K}^4$  Stephan constant

$e$  - emissivity, describes the capacity of the object to absorb energy  $0 < e < 1$

Such thermal radiation is often called black body radiation

Black body is an object that absorbs all radiation falling on its surface and then emits it with perfect emissivity  $e=1$

The origin of BB radiation is the microscopic motion of ~~atoms~~<sup>ions</sup> and of electrons inside atoms/molecules, since every moving charged particle has to emit e-m waves

Planck's law

$$I(\lambda, T) = \frac{2\pi hc^2}{\lambda^5} \frac{1}{e^{hc/\lambda k_B T} - 1}$$

$h$  - planck's constant

$\hbar = h/2\pi$  - Heisenberg constant

$$\lambda_{max} \cdot T = const$$

